

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hsiang-Ming Chou</td> <td>03/21/2012</td> </tr> <tr> <td>Kuo-Liang Pan</td> <td>03/21/2012</td> </tr> <tr> <td>Chien-Feng Tseng</td> <td>03/21/2012</td> </tr> <tr> <td>Yi-Chiu Tsai</td> <td>03/21/2012</td> </tr> <tr> <td>Chien-Shao Tang</td> <td>03/21/2012</td> </tr> <tr> <td>Hsin-Han Chen</td> <td>03/21/2012</td> </tr> </tbody> </table>		Name	Execution Date	Hsiang-Ming Chou	03/21/2012	Kuo-Liang Pan	03/21/2012	Chien-Feng Tseng	03/21/2012	Yi-Chiu Tsai	03/21/2012	Chien-Shao Tang	03/21/2012	Hsin-Han Chen	03/21/2012
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<table border="1"> <tr> <td>Name:</td> <td>Elite Semiconductor Memory Technology Inc.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 23, INDUSTRY E. RD. IV, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	Elite Semiconductor Memory Technology Inc.	Street Address:	NO. 23, INDUSTRY E. RD. IV, SCIENCE-BASED INDUSTRIAL PARK	City:	HSINCHU	State/Country:	TAIWAN						
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<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13430649</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13430649										
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Application Number:	13430649														
CORRESPONDENCE DATA															
<p>Fax Number: (703)997-4517</p> <p>Phone: 3027291562</p> <p>Email: Patent.admin.uspto.cr@naipo.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: WINSTON HSU</p> <p>Address Line 1: P.O.BOX 506</p> <p>Address Line 4: Merrifield, VIRGINIA 22116</p>															
ATTORNEY DOCKET NUMBER:	ESMP0001USA														
NAME OF SUBMITTER:	SHELLEY KUO														

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Total Attachments: 4

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PATENT

REEL: 027930 FRAME: 0518

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Hsiang-Ming Chou Nationality: TW

Name: Kuo-Liang Pan Nationality: TW

Name: Chien-Feng Tseng Nationality: TW

Name: Yi-Chiu Tsai Nationality: TW

Name: Chien-Shao Tang Nationality: TW

Name: Hsin-Han Chen Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Elite Semiconductor Memory Technology Inc.

Address: NO. 23, INDUSTRY E. RD. IV, SCIENCE-BASED INDUSTRIAL PARK,
HSINCHU 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"CONFIGURABLE ELECTROSTATIC DISCHARGING POWER CLAMP AND RELATED INTEGRATED CIRCUIT"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____
- (e) _____ International application no. _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 3/21/2012 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Hsiang-Ming Chou

Hsiang-Ming J. Chou

Kuo-Liang Pan

Kuo Liang Pan

Chien-Feng Tseng

Chien-Feng Tseng

Yi-Chiu Tsai

Yi Chiu Tsai

Chien-Shao Tang

Chien-Shao Tang

Hsin-Han Chen

Hsin Han Chen

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NPO#ESM-P0001-USA:0
CUST#ES11015

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F#NPO-P0002E-US1
DSC0-101U003176

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RECORDED: 03/26/2012

REEL: 027930 FRAME: 0522